



## Product Change Notification / ALAN-21QQJQ976

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### Date:

26-Feb-2024

### Product Category:

Power Discrete Components

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 6500 Initial Notice: Qualification of MG15F-0140B as the new mold compound for selected MSC01xx, MSC03xx, MSC09xx, MSC18xx, MSC04xx, MSC05xx, MSC36xx, MSC06xx, MSC02xx, MSC75xx, and MSC08xx device families available in 2L TO-268 package.

### Affected CPNs:

[ALAN-21QQJQ976\\_Affected\\_CPN\\_02262024.pdf](#)

[ALAN-21QQJQ976\\_Affected\\_CPN\\_02262024.csv](#)

### Notification Text:

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of MG15F-0140B as the new mold compound for selected MSC01xx, MSC03xx, MSC09xx, MSC18xx, MSC04xx, MSC05xx, MSC36xx, MSC06xx, MSC02xx, MSC75xx, and MSC08xx device families available in 2L TO-268 package.

### Pre and Post Change Summary:

	Pre Change		Post Change	
Assembly Site	TEAM PACIFIC CORPORATION (TEAM)		TEAM PACIFIC CORPORATION (TEAM)	
Wire Material	Al		Al	
Die Attach Material	PbSn2Ag2.5	PbSn5Ag2.5	PbSn2Ag2.5	PbSn5Ag2.5
Molding Compound Material	MG15F-0140		MG15F-0140B	
Lead-Frame Material	Cu		Cu	

**Impacts to Data Sheet:**None

**Change Impact**None

**Reason for Change:**To improve manufacturability by qualifying MG15F-0140B as the new mold compound.

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**May 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	February 2024					>	May 2024				
Workweek	05	06	07	08	09		18	19	20	21	22
Initial PCN Issue Date					X						
Qual Report Availability							X				
Final PCN Issue Date							X				

**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**February 26, 2024: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_ALAN-21QQJQ976 Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MSC010SDA070S  
MSC035SMA070S  
MSC090SMA070S  
MSC035SMA170S  
MSC180SMA120S  
MSC040SMA120S  
MSC015SMA070S  
MSC050SDA070S  
MSC050SDA120S  
MSC360SMA120S  
MSC017SMA120S  
MSC030SDA070S  
MSC060SMA070S  
MSC020SDA120S  
MSC750SMA170S  
MSC025SMA120S  
MSC030SDA120S  
MSC080SMA120S  
MSC040SMA120S/TR